Digital-linear Microcircuit - Page 1 of 1



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1.400 inches Body Width: D.805 inches Body Height: D.200 inches Maximum Power Dissipation Rating: Maximum Power Dissipation Rating: Storage Tempurature Range: Storage Tempurature Rang	
D.805 inches   Body Height:   D.200 inches   Maximum Power Dissipation Rating:   B10.0 milliwatts   Operating Tempurature Range:   .55.0 to 125.0 degrees celsius   Storage Tempurature Range:   .65.0 to 125.0 degrees celsius   Features Provided:   Fast settling and hybrid and hermetically sealed   Inclosure Material:   Ceramic or metal   Inclosure Configuration:   Dual-in-line   Dutput Logic Form:   Metal oxide-semiconductor logic   Input Circuit Pattern:   16 input   Design Function And Quantity:   1 converter, digital to analog   Terminal Surface Treatment:   Solder	
Body Height:   0.200 inches   Maximum Power Dissipation Rating:   310.0 milliwatts   Operating Tempurature Range:   .55.0 to 125.0 degrees celsius   Storage Tempurature Range:   .65.0 to 125.0 degrees celsius   Features Provided:   =ast settling and hybrid and hermetically sealed   nclosure Material:   Ceramic or metal   nclosure Configuration:   Dual-in-line   Dutput Logic Form:   Wetal oxide-semiconductor logic   nput Circuit Pattern:   16 input   Design Function And Quantity:   1 converter, digital to analog   Terminal Surface Treatment:   Solder	
D.200 inches         Maximum Power Dissipation Rating:         B10.0 milliwatts         Operating Tempurature Range:         -55.0 to 125.0 degrees celsius         Storage Tempurature Range:         -65.0 to 125.0 degrees celsius         Features Provided:         Fast settling and hybrid and hermetically sealed         Inclosure Material:         Ceramic or metal         nclosure Configuration:         Dual-in-line         Dutput Logic Form:         Metal oxide-semiconductor logic         Input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
Maximum Power Dissipation Rating:         B10.0 milliwatts         Operating Tempurature Range:         -55.0 to 125.0 degrees celsius         Storage Tempurature Range:         -65.0 to 125.0 degrees celsius         Features Provided:         Fast settling and hybrid and hermetically sealed         Inclosure Material:         Ceramic or metal         nclosure Configuration:         Dual-in-line         Dutput Logic Form:         Metal oxide-semiconductor logic         input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
B10.0 milliwatts         Operating Tempurature Range:         455.0 to 125.0 degrees celsius         Storage Tempurature Range:         455.0 to 125.0 degrees celsius         Features Provided:         Fast settling and hybrid and hermetically sealed         Inclosure Material:         Ceramic or metal         Inclosure Configuration:         Dual-in-line         Dutput Logic Form:         Metal oxide-semiconductor logic         Input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
Operating Tempurature Range:         55.0 to 125.0 degrees celsius         Storage Tempurature Range:         65.0 to 125.0 degrees celsius         Features Provided:         Fast settling and hybrid and hermetically sealed         Inclosure Material:         Ceramic or metal         Inclosure Configuration:         Dual-in-line         Dutput Logic Form:         Metal oxide-semiconductor logic         Input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
55.0 to 125.0 degrees celsius         Storage Tempurature Range:         65.0 to 125.0 degrees celsius         Features Provided:         Fast settling and hybrid and hermetically sealed         inclosure Material:         Ceramic or metal         Inclosure Configuration:         Dual-in-line         Dutput Logic Form:         Metal oxide-semiconductor logic         Input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
Storage Tempurature Range: 65.0 to 125.0 degrees celsius Features Provided: Fast settling and hybrid and hermetically sealed Inclosure Material: Ceramic or metal Inclosure Configuration: Dual-in-line Dual-in-line Dutput Logic Form: Metal oxide-semiconductor logic Input Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Ferminal Surface Treatment: Solder	
A65.0 to 125.0 degrees celsius Features Provided: Fast settling and hybrid and hermetically sealed Inclosure Material: Ceramic or metal Inclosure Configuration: Dual-in-line Dutput Logic Form: Metal oxide-semiconductor logic Input Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Ferminal Surface Treatment: Solder	
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Fast settling and hybrid and hermetically sealed         Inclosure Material:         Ceramic or metal         Inclosure Configuration:         Dual-in-line         Dutput Logic Form:         Metal oxide-semiconductor logic         Input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
Inclosure Material: Ceramic or metal Inclosure Configuration: Dual-in-line Dutput Logic Form: Metal oxide-semiconductor logic Input Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Terminal Surface Treatment: Solder	
Ceramic or metal Inclosure Configuration: Dual-in-line Dutput Logic Form: Metal oxide-semiconductor logic Input Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Terminal Surface Treatment: Solder	
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Dual-in-line Dutput Logic Form: Metal oxide-semiconductor logic nput Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Terminal Surface Treatment: Solder	
Dutput Logic Form:         Metal oxide-semiconductor logic         Input Circuit Pattern:         16 input         Design Function And Quantity:         1 converter, digital to analog         Terminal Surface Treatment:         Solder	
Metal oxide-semiconductor logic input Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Ferminal Surface Treatment: Solder	
Input Circuit Pattern: 16 input Design Function And Quantity: 1 converter, digital to analog Terminal Surface Treatment: Solder	
16 input <b>Design Function And Quantity:</b> 1 converter, digital to analog <b>Ferminal Surface Treatment:</b> Solder	
<b>Design Function And Quantity:</b> 1 converter, digital to analog <b>Terminal Surface Treatment:</b> Solder	
1 converter, digital to analog <b>Terminal Surface Treatment:</b> Solder	
<b>Terminal Surface Treatment:</b> Solder	
Solder	
Voltage Rating And Type Per Characteristic:	
18.0 volts power source	
Test Data Document:	
96906-mil-std-883 standard (includes industry or association standards, individu	al manufactureer standards, etc.).
Terminal Type And Quantity:	
24 printed circuit	
Shelf Life:	
N/a	
Unit Of Measure:	
-	
Demilitarization:	
Yes - demil/mli	
Fiig:	
A458a0	